



Material Composition Declaration

EPC2016

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	6.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	5.4032	86.13	88.07	861345
	Silicon oxide	7631-86-9	0.0209	0.33		3324
	Silicon nitride	12033-89-5	0.0066	0.11		1056
	Gallium nitride	25617-97-4	0.0255	0.41		4057
	Aluminum	7429-90-5	0.0407	0.65		6489
	Aluminum nitride	24304-00-5	0.0061	0.10		978
	Titanium	7440-32-6	0.0009	0.01		146
	Titanium nitride	25583-20-4	0.0036	0.06		581
	Copper	7440-50-8	0.0014	0.02		216
	Tungsten	7440-33-7	0.0011	0.02		171
	Polyimide		0.0145	0.23		2314
Under Bump Metal	Titanium	7440-32-6	0.0012	0.02	0.22	185
	Nickel	7440-02-0	0.0035	0.06		552
	Vanadium	7440-62-2	0.0002	0.00		28
	Copper	7440-50-8	0.0092	0.15		1470
Solder Bump	Tin	7440-31-5	0.7014	11.18	11.71	111818
	Silver	7440-22-4	0.0294	0.47		4683
	Copper	7440-50-8	0.0037	0.06		585
Sum in total:			6.3	100	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.